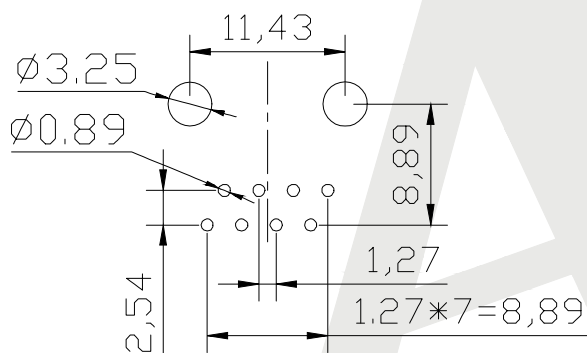
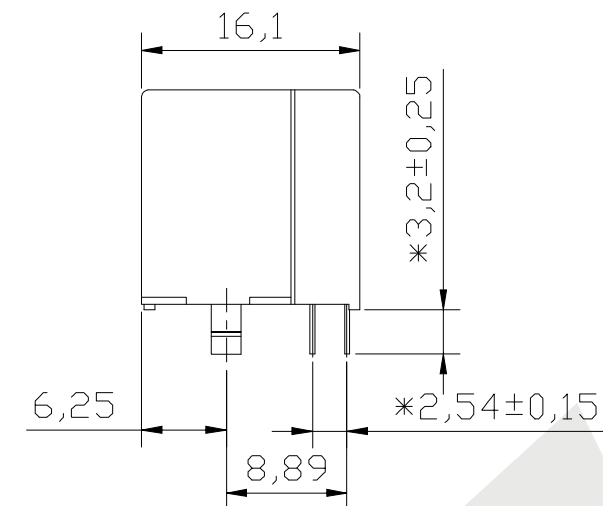
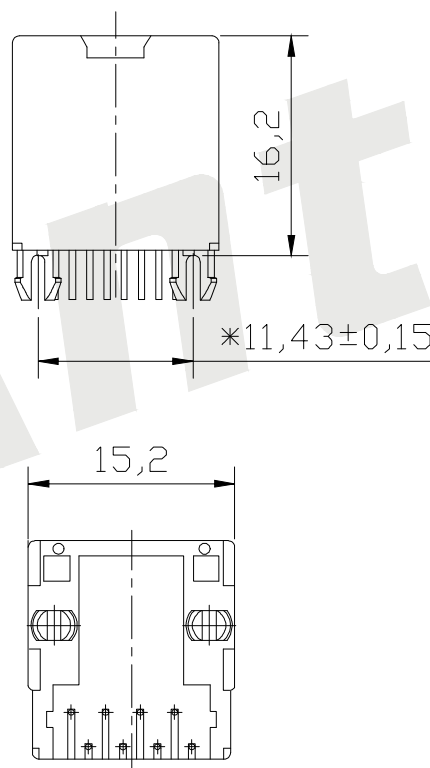
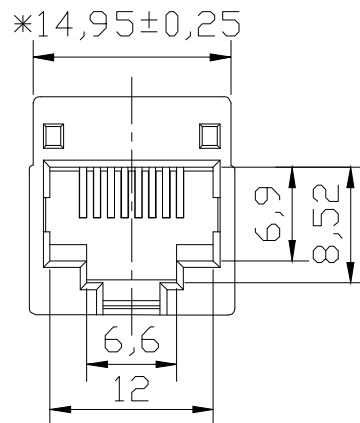


HSF



ROHS

PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL :PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING :SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD :0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING :125VAC RMS
2. CURRENT RATING :1.5AMP
3. CONTACT RESISTANCE:30 MILLIOHMS MAX
4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY :750 CYCLES MIN
 2. PCB RETENTTON PRB-SOLDER :1 LB MIN
- REVIROMENTAL
1. STORAGE : -40°C TO 85°C
 2. OPERATION : 0°C TO 70°C

Order code:

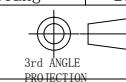
ATRJ5222 - 8P - 8C - G0 - A - A
① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
② NUMBER OF POSITIONS (8P, 6P, 4P)
③ NUMBER OF CONTACTS (8C, 6C, 4C)
④ Contact Plating
G0:Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin

- ⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
⑥ Ports
A:1X1P
B:1X2P
C:1X4P
D:1X5P
E:1X6P
F:1X8P

Unless Otherwise specified tolerance
X. ± 0.35 X. XX: ± 0.20
X. X: ± 0.25 X. XXX: ± 0.15

SCALE:
As Shown
DRAW
Wu Feng Rong
CHECK
BobYang



UNIT:
mm
DATE
25/07/2019
DATE
25/07/2019



ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: Modular Jack Top Entry,
8P8C, 1X1Port Full Plastic

DRAWING NO: ATRJ5222-8P8C-G0-A-A

PRODUCT NO: ATRJ5222-8P8C-G0-A-A

REV

DESCRIPTION

DATE

1

2

3

4

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6

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